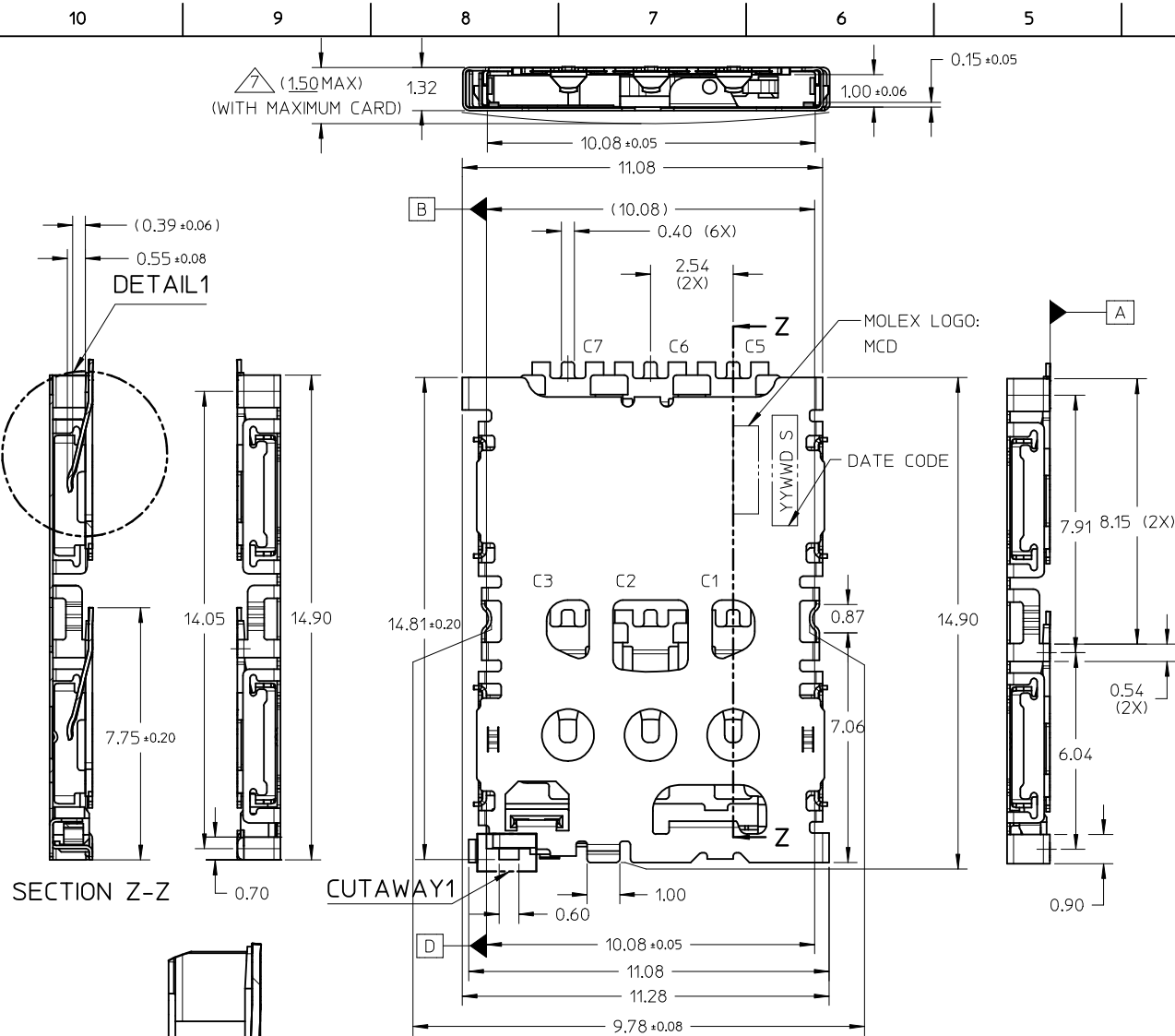


(1.50 MAX)
(WITH MAXIMUM CARD)



NOTES:

1. MATERIALS:

1.1 CONNECTOR:-

INSERT MOLD HOUSING: LCP, GLASS FILLED, UL94V-0, COLOUR BLACK.

TERMINAL: TITANIUM COPPER, THICKNESS: 0.12MM

DETECT PIN: TITANIUM COPPER, THICKNESS: 0.12MM

SHELL: STAINLESS STEEL, THICKNESS: 0.10MM

2. PLATING FINISHES:

2.1 TERMINAL:-

CONTACT: 0.38um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.

SOLDERTAIL: 0.025um MIN. GOLD FLASH OVER 2.00um MIN. NICKEL UNDERPLATE.

2.2 SHELL:-

CONTACT: 0.05um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.

SOLDERTAIL: 0.025um MIN. GOLD FLASH OVER 2.00um MIN. NICKEL UNDERPLATE.

2.3 DETECT PIN:-

CONTACT: 0.127um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.

SOLDERTAIL: 1.27um MIN. MATTE TIN OVER 2.00um MIN. NICKEL UNDERPLATE.

3. PRODUCT SPECIFICATION: PS-151073-0001

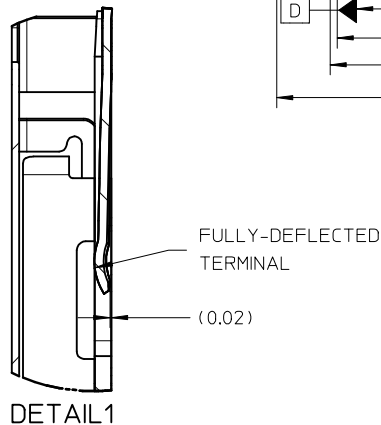
4. PACKAGING SPECIFICATION: PK-151073-0001

5. OVERALL (SOLDERTAIL & SOLDERTAB) COPLANARITY 0.08MM MAX. BEFORE REFLOW.

6. CONNECTOR TO BE USED TOGETHER WITH MOLEX NANO SIM CARD TRAY ONLY.

△ DIMENSION INCLUSIVE OF BULGE

THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.



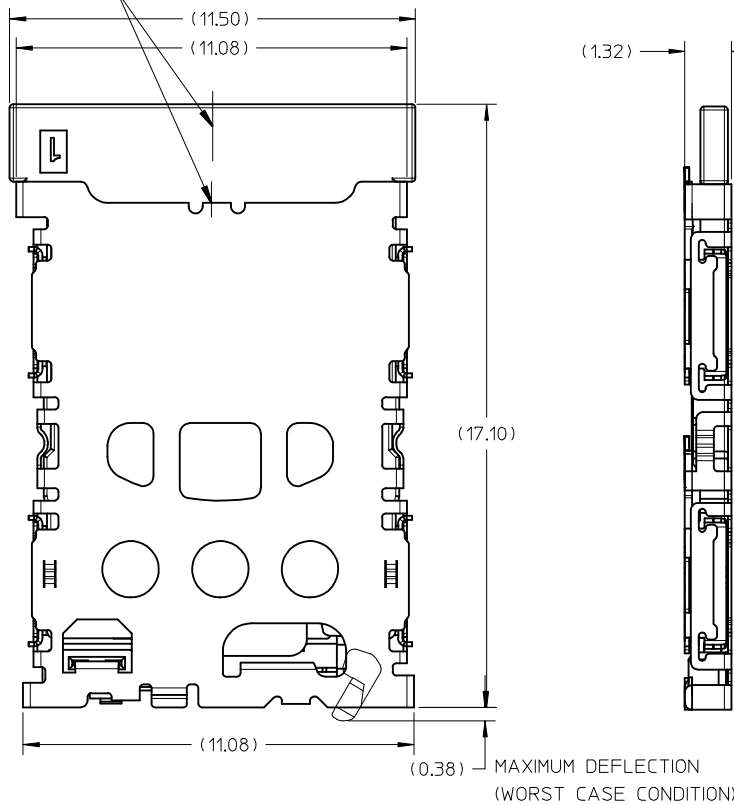
ADD TOL TO CONTACT TIP EC NO: S2015-0916 DRWN: SCHEONG CHKD: GMENARLY APPR: KHL IM	QUALITY SYMBOLS	DESCRIPTION
	$F_A = 0$	
	$F_C = 0$	
	$F_P = 0$	
12	REV	

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
	± ---	± ---
4 PLACES	± ---	± ---
	± ---	± ---
3 PLACES	± ---	± ---
	± ---	± ---
2 PLACES	± 0.10	± ---
	± ---	± ---
1 PLACE	± ---	± ---
	± ---	± ---
0 PLACE	± ---	± ---
	± ---	± ---
ANGULAR ± 3 °		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		

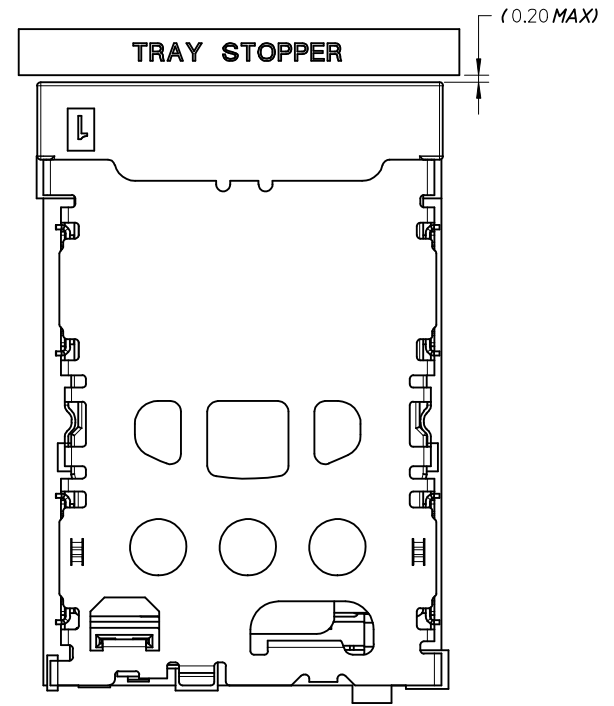
DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
DRAWN BY SCHEONG	DATE 2014/07/16	TITLE NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN		
CHECKED BY GMENARLY	DATE 2015/03/10	DOCUMENT NO. SD-151073-0001		
APPROVED BY KHL IM	DATE 2015/03/12	SHEET NO. 1 OF 3		
MATERIAL NO. SEE TABLE				
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

10 9 8 7 6 5 4 3 2 1

CENTRELINES OF TRAY AND CONNECTOR OPENING ARE THE SAME



CONNECTOR WITH TRAY



SYSTEM LEVEL

DESCRIPTION	PART NUMBER
CONNECTOR	151073-1000
NANO SIM CARD TRAY	151073-0011

CARD INSERTION STATE	DETECT SWITCH CIRCUIT STATE	SCHEMATIC
CARD MATED	OPENED	
CARD UNMATED	CLOSED	

ADD TOL TO CONTACT TIP	DESCRIPTION
EC NO: S2015-0916	
DRWN:SCHEONG	2015/03/03
CHKD:GMENARLY	2015/03/10
APPR:KHL IM	2015/03/12
12	

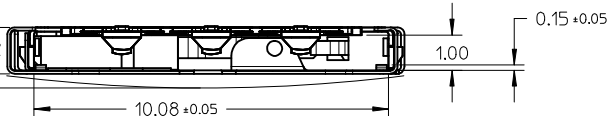
QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	
	mm	INCH
$F_{A=0}$	4 PLACES	± --- ± ---
$F_{C=0}$	3 PLACES	± --- ± ---
$F_{P=0}$	2 PLACES	± 0.10 ± ---
	1 PLACE	± --- ± ---
	0 PLACE	± --- ± ---
	ANGULAR ± 3 °	
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
MM ONLY		NTS	METRIC	
DRAWN BY	DATE	TITLE		
SCHEONG	2014/07/16	NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN		
CHECKED BY	DATE	molex		
GMENARLY	2015/03/10			
APPROVED BY	DATE	DOCUMENT NO. SD-151073-0001		
KHL IM	2015/03/12	SHEET NO. 2 OF 3		
MATERIAL NO.	SEE TABLE			
SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
A3				

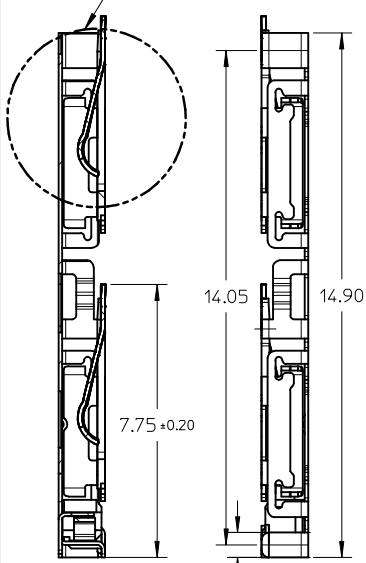
9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

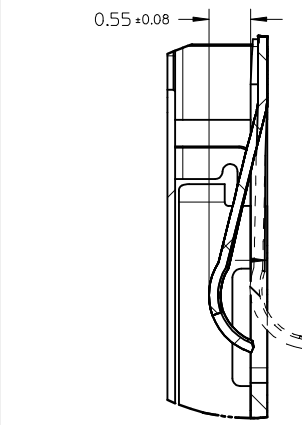
△ (1.50 MAX)
(WITH MAXIMUM CARD)



DETAIL1

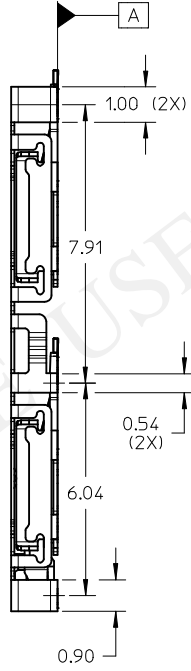
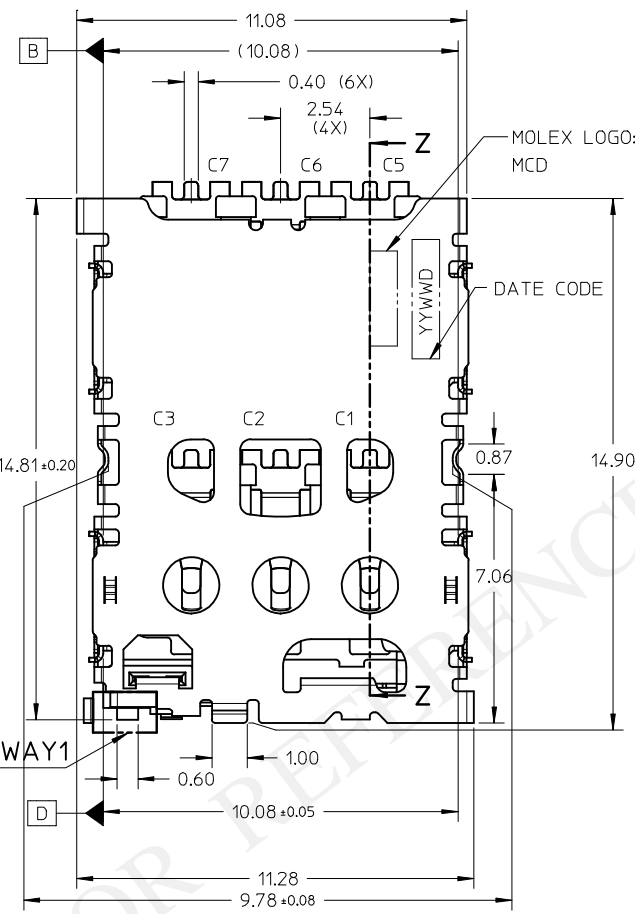


SECTION Z-Z



DETAIL1

CUTAWAY1



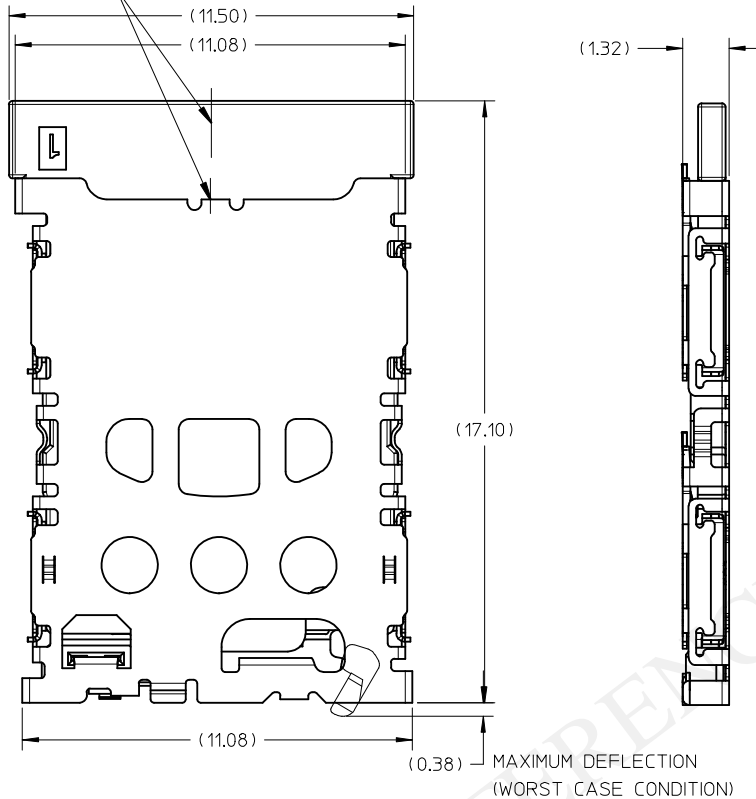
NOTES:

1. MATERIALS:
 - 1.1 CONNECTOR:-
 - INSERT MOLD HOUSING: LCP, GLASS FILLED, UL94V-0, COLOUR BLACK.
 - TERMINAL: TITANIUM COPPER, THICKNESS: 0.12MM
 - DETECT PIN: TITANIUM COPPER, THICKNESS: 0.12MM
 - SHELL: STAINLESS STEEL, THICKNESS: 0.10MM
 - 2. PLATING FINISHES:
 - 2.1 TERMINAL:-
 - CONTACT: 0.38um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.
 - SOLDERTAIL: 0.025um MIN. GOLD FLASH OVER 2.00um MIN. NICKEL UNDERPLATE.
 - 2.2 SHELL:-
 - CONTACT: 0.05um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.
 - SOLDERTAIL: 0.025um MIN. GOLD FLASH OVER 2.00um MIN. NICKEL UNDERPLATE.
 - 2.3 DETECT PIN:-
 - CONTACT: 0.127um MIN. GOLD ON CONTACT AREA OVER 2.00um MIN. NICKEL UNDERPLATE.
 - SOLDERTAIL: 1.27um MIN. MATTE TIN OVER 2.00um MIN. NICKEL UNDERPLATE.
 - 3. PRODUCT SPECIFICATION: PS-151073-0001
 - 4. PACKAGING SPECIFICATION: PK-151073-0001
 - 5. OVERALL (SOLDERTAIL & SOLDERTAB) COPLANARITY 0.08MM MAX. BEFORE REFLOW.
 - 6. CONNECTOR TO BE USED TOGETHER WITH MOLEX NANO SIM CARD TRAY ONLY.
 - △ DIMENSION INCLUSIVE OF BULGE
 - 8. CUSTOMER STENCIL THICKNESS: 0.10 ~ 0.12mm AND STENCIL OPENING: 1:1 MIN , 1:1.5 MAX

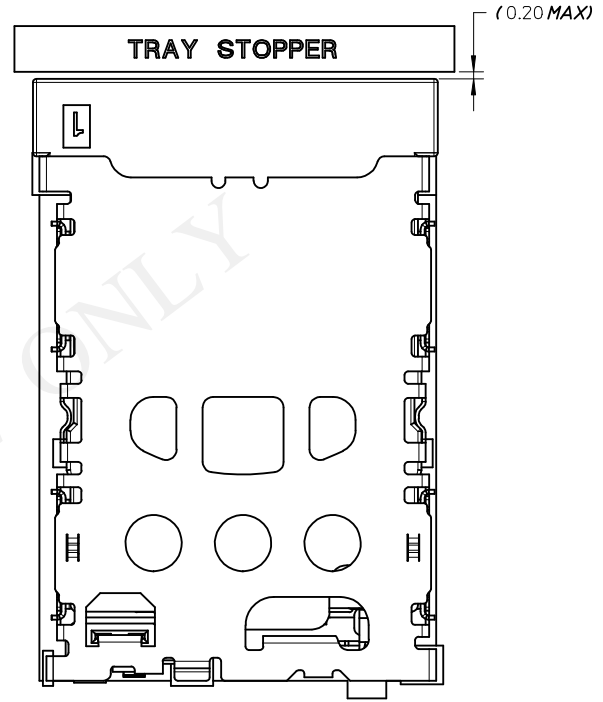
PRELIM. RELEASE EC NO: S2016-0054 DRWNS: SCHEONG 2015/07/07 CHKD: APPR: SCHEONG 2015/07/14 REV	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
	▽F=0	mm	INCH	MM ONLY		NTS	METRIC		
	▽F=6	4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	DRAWN BY	DATE	TITLE			
	▽F=0	2 PLACES ± 0.10 ± ---	1 PLACE ± --- ± ---	CHECKED BY	DATE	NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN			
		0 PLACE ± --- ± ---	ANGULAR ± 3 °		APPROVED BY	DATE	molex		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
				SEE TABLE		SD-151073-0010		1 OF 3	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

9 8 7 6 5 4 3 2 1

CENTRELINES OF TRAY AND CONNECTOR OPENING ARE THE SAME



CONNECTOR WITH TRAY

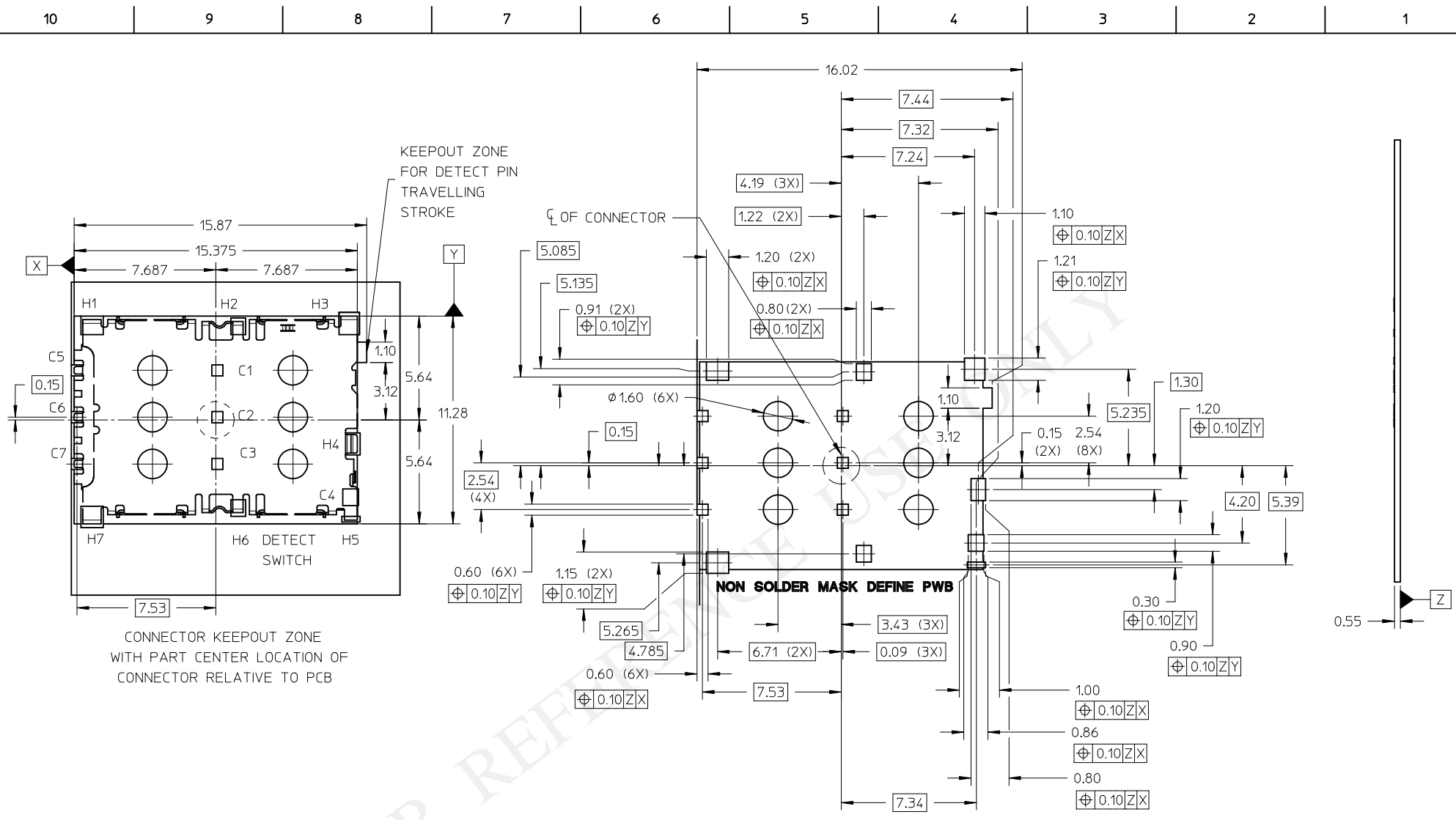


SYSTEM LEVEL

DESCRIPTION	PART NUMBER
CONNECTOR	151073-0001
NANO SIM CARD TRAY	151073-0030

CARD INSERTION STATE	DETECT SWITCH CIRCUIT STATE	SCHEMATIC
CARD MATED	OPENED	
CARD UNMATED	CLOSED	

PRELIM. RELEASE EC NO: S2016-0054 DRWNS: SCHEONG 2015/07/07 CHKD: APPR: SCHEONG 2015/07/14	QUALITY SYMBOLS $\nabla = 0$ $\nabla = 0$ $\nabla = 0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		4 PLACES \pm --- \pm --- 3 PLACES \pm --- \pm --- 2 PLACES ± 0.10 \pm --- 1 PLACE \pm --- \pm --- 0 PLACE \pm --- \pm ---	DRAWN BY SCHEONG	DATE 2015/07/07	TITLE NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN		
		ANGULAR $\pm 3^\circ$	APPROVED BY SCHEONG	DATE 2015/07/14	molex		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-151073-0010	SHEET NO. 2 OF 3		



RECOMMENDED PWB LAYOUT
 (NON SOLDER MASK DEFINE PWB)
 PWB TOLERANCE: ±0.05MM

PRELIM. RELEASE EC NO: S2016-0054 DRWN: SCHEONG CHKD: APPR: SCHEONG 2015/07/07 2015/07/14	QUALITY SYMBOLS $F=0$ $F=0$ $F=0$	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± --- ± --- 3 PLACES ± --- ± --- 2 PLACES ± 0.10 ± --- 1 PLACE ± --- ± --- 0 PLACE ± --- ± ---	mm INCH	DRAWN BY SCHEONG	DATE 2015/07/07	TITLE NANO SIM CONNECTOR 1.32MM HEIGHT WITH TRAY AND DETECT PIN			
		ANGULAR ± 3 °		CHECKED BY	DATE	molex			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SCHEONG	DATE 2015/07/14	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-151073-0010	SHEET NO. 3 OF 3	



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

Телефон: 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: org@eplast1.ru

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, дом 2, корпус 4, литера А.